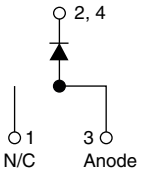
Hyperfast Rectifier, 5 A FRED Pt®

DPAK (TO-252AA)



FEATURES

- Hyperfast recovery time, reduced Q_{rr} and soft recovery
- 175 °C maximum operating junction temperature
- For PFC CRM/CCM operation
- Low forward voltage drop
- Low leakage current
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified
- Meets JESD 201 class 2 whisker test
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

RoHS COMPLIANT

HALOGEN FREE

PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	5 A
V_R	600 V
V_F at I_F	1.2 V
t_{rr} (typ.)	18 ns
T_J max.	175 °C
Package	DPAK (TO-252AA)
Circuit configuration	Single

DESCRIPTION / APPLICATIONS

State of the art hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time, and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC boost stage in the AC/DC section of SMPS inverters or as freewheeling diodes. Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Peak repetitive reverse voltage	V_{RRM}		600	V
Average rectified forward current	$I_{F(AV)}$	T_C = 150 °C	5	A
Non-repetitive peak surge current	I_{FSM}	T_J = 25 °C	70	
Peak repetitive forward current	I_{FM}	T_C = 150 °C, f = 20 kHz, d = 50 %	10	
Operating junction and storage temperatures	T_J, T_{Stg}		-65 to +175	°C

ELECTRICAL SPECIFICATIONS (T_J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	V_{BR}, V_R	I_R = 100 µA	600	-	-	V
Forward voltage	V_F	I_F = 5 A	-	1.54	1.85	
		I_F = 5 A, T_J = 150 °C	-	1.20	1.40	
Reverse leakage current	I_R	V_R = V_R rated	-	-	5	µA
		T_J = 150 °C, V_R = V_R rated	-	-	130	
Junction capacitance	C_T	V_R = 600 V	-	3.5	-	pF
Series inductance	L_S	Measured lead to lead 5 mm from package body	-	8	-	nH

DYNAMIC RECOVERY CHARACTERISTICS (T_J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Reverse recovery time	t_{rr}	I_F = 1 A, dI_F/dt = 100 A/µs, V_R = 30 V		-	18	-	ns
		I_F = 1 A, dI_F/dt = 50 A/µs, V_R = 30 V		-	22	-	
		T_J = 25 °C	I_F = 5 A dI_F/dt = 200 A/µs V_R = 390 V	-	25	-	
		T_J = 125 °C		-	35	-	
Peak recovery current	I_{RRM}	T_J = 25 °C		-	3.9	-	A
		T_J = 125 °C		-	5.1	-	
Reverse recovery charge	Q_{rr}	T_J = 25 °C		-	51	-	nC
		T_J = 125 °C		-	93	-	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	T_J, T_{Stg}		-65	-	175	°C
Thermal resistance, junction to case per leg	R_{thJC}		-	-	3	°C/W
Approximate weight			0.3			g
			0.01			oz.
Marking device		Case style DPAK (TO-252AA)	5EWH06FNH			

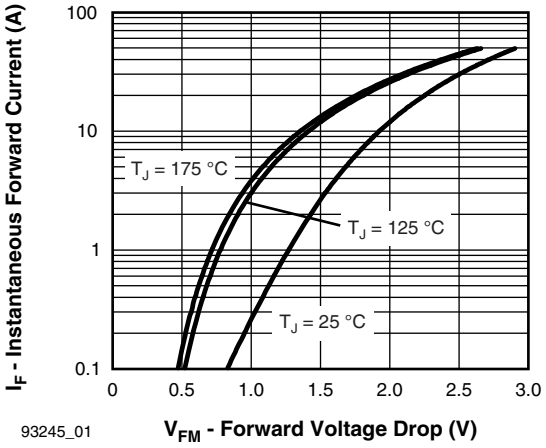


Fig. 1 - Typical Forward Voltage Drop Characteristics

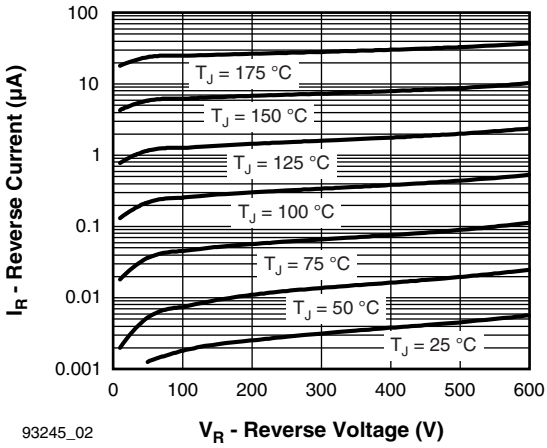


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

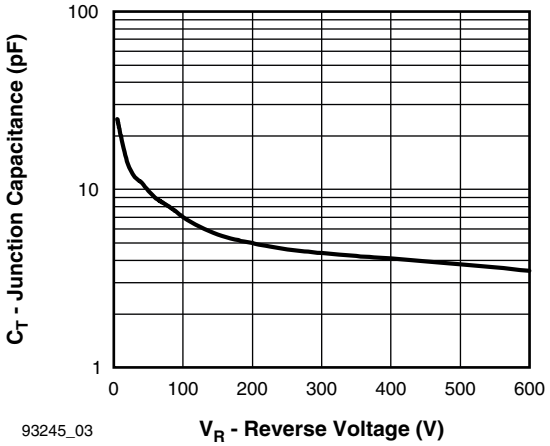


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

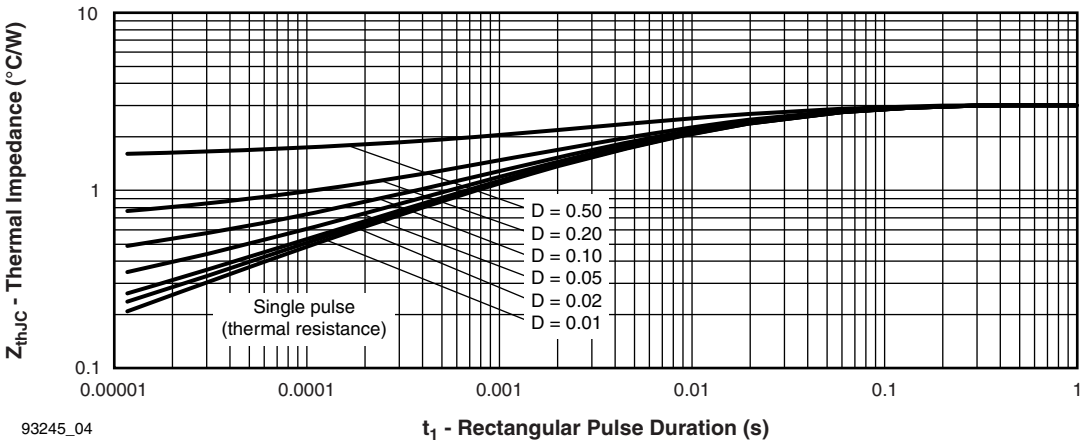


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

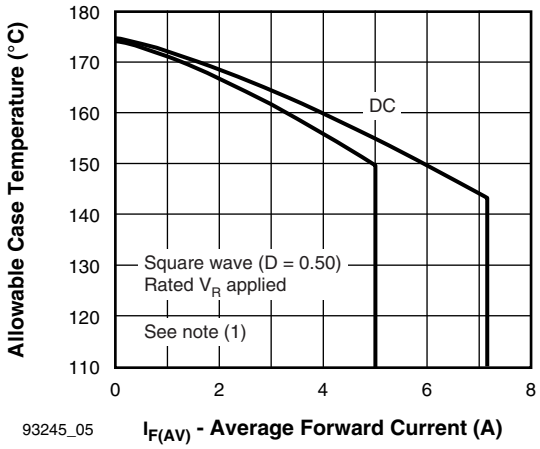


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

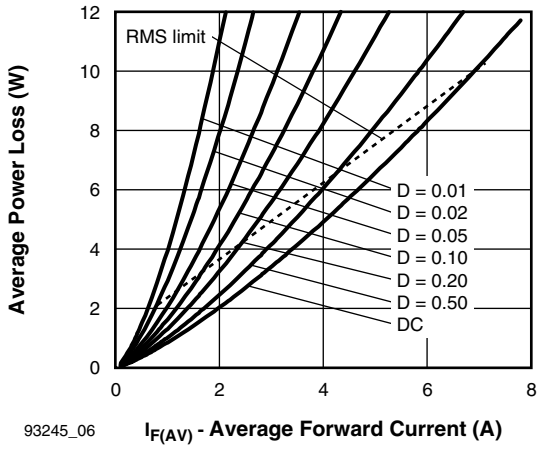


Fig. 6 - Forward Power Loss Characteristics

Note

(1) Formula used: $T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}$;
Pd = forward power loss = $I_{F(AV)} \times V_{FM}$ at ($I_{F(AV)}$/D) (see fig. 6);
Pd_{REV} = inverse power loss = $V_{R1} \times I_R (1 - D)$; I_R at V_{R1} = rated V_R

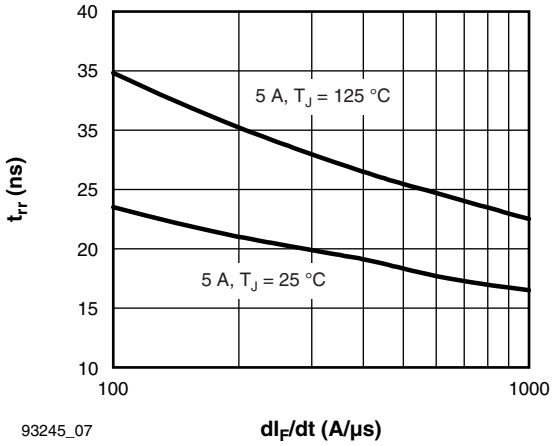


Fig. 7 - Typical Reverse Recovery Time vs. dI_F/dt

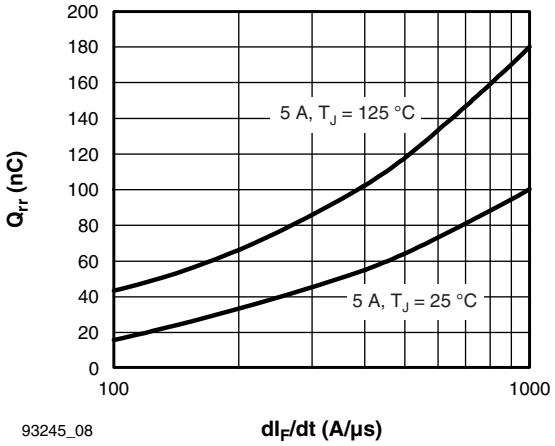
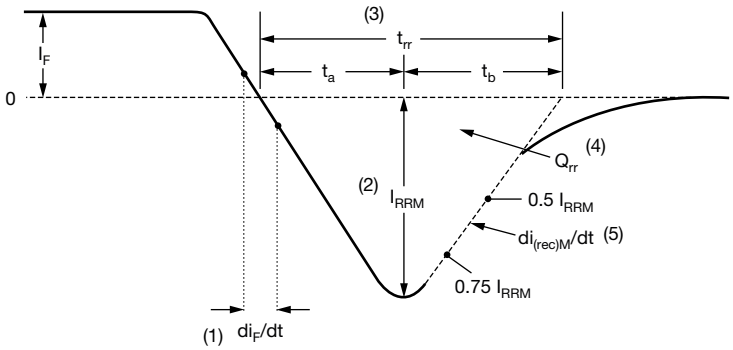


Fig. 8 - Typical Stored Charge vs. dI_F/dt



(1) di_F/dt - rate of change of current through zero crossing

(2) I_{RRM} - peak reverse recovery current

(3) t_{rr} - reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RRM} and 0.50 I_{RRM} extrapolated to zero current.

(4) Q_{rr} - area under curve defined by t_{rr} and I_{RRM}

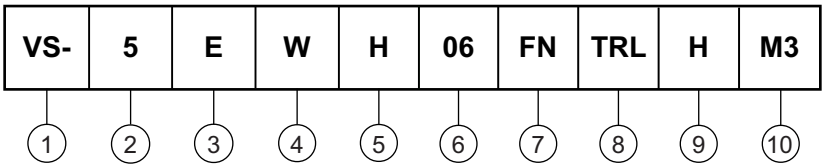
$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) $di_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Fig. 9 - Reverse Recovery Waveform and Definitions

ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - Current rating (5 = 5 A)

3 - Circuit configuration:
E = single diode

4 - Package identifier:
W = D-PAK

5 - H = hyperfast recovery

6 - Voltage rating (06 = 600 V)

7 - FN = TO-252AA

8 -
- None = tube
- TR = tape and reel
- TRL = tape and reel (left oriented)
- TRR = tape and reel (right oriented)

9 - H = AEC-Q101 qualified

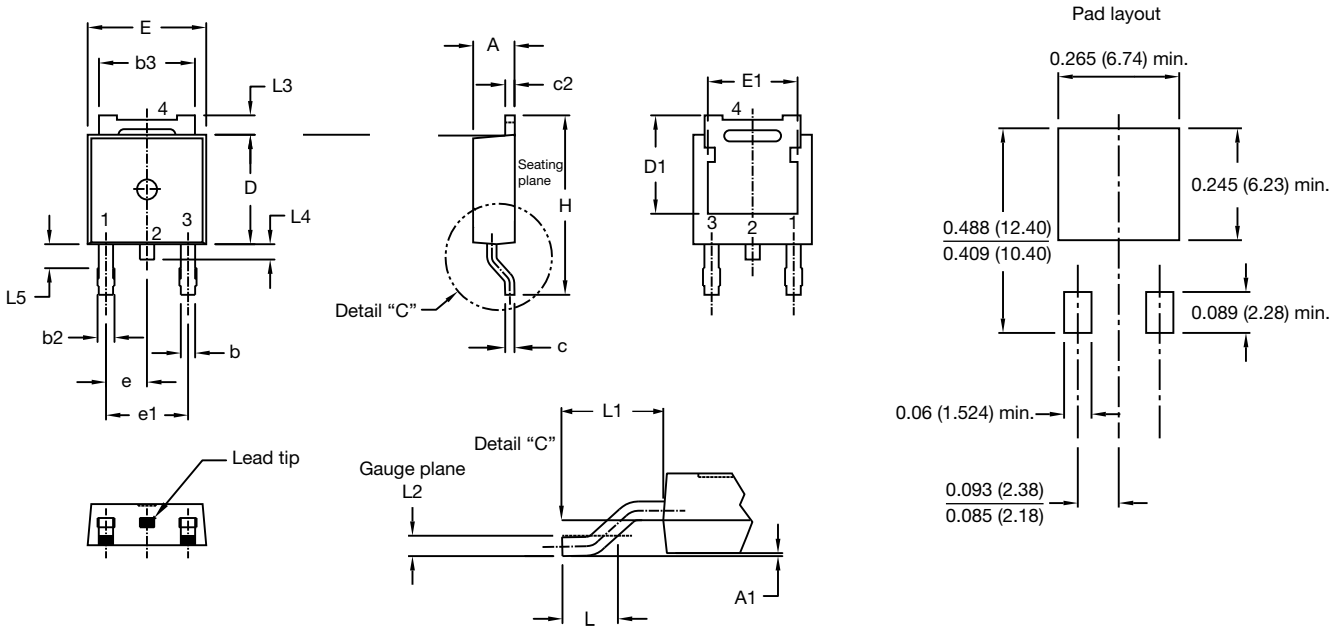
10 - Environmental digit:
M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)		
PREFERRED P/N	**BASE QUANTITY**	**PACKAGING DESCRIPTION**
VS-5EWH06FNHM3	75	Antistatic plastic tube
VS-5EWH06FNTRHM3	2000	13" diameter reel
VS-5EWH06FNTRLHM3	3000	13" diameter reel
VS-5EWH06FNTRRHM3	3000	13" diameter reel

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95519
Part marking information	www.vishay.com/doc?95176
Packaging information	www.vishay.com/doc?95518
SPICE model	www.vishay.com/doc?95186

DPAK (TO-252AA)

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	2.18	2.39	0.086	0.094	
A1	-	0.13	-	0.005	
b	0.64	0.89	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	3
c	0.46	0.61	0.018	0.024	
c2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	5
D1	4.93	-	0.194	-	3
E	6.35	6.73	0.250	0.265	5
E1	4.32	-	0.170	-	3

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
e	2.29 BSC		0.090 BSC		
H	9.40	10.41	0.370	0.410	
L	1.40	1.78	0.055	0.070	
L1	2.74 BSC		0.108 REF.		
L2	0.51 BSC		0.020 BSC		
L3	0.89	1.27	0.035	0.050	3
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	2

Notes

(1) Dimensioning and tolerancing as per ASME Y14.5M-1994

(2) Lead dimension uncontrolled in L5

(3) Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad

(4) Dimensions D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body

(5) Outline conforms to JEDEC® outline TO-252AA, except for D1 dimension

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